

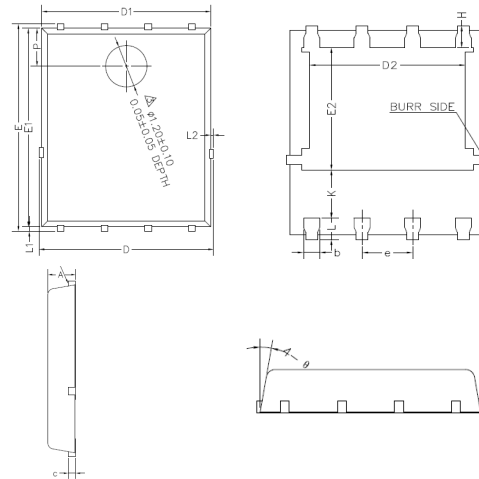
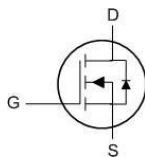
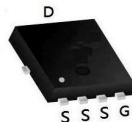
**Description**

The 80N03NF is the high cell density Trench MOSFET, which provide excellent RDSON and gate charge for DC/DC converters application.

The 80N03NF meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

100% EAS Guaranteed  
Green Device Available  
Super Low Gate Charge  
Low  $R_{DS(ON)}$

Advanced high cell density Trench technology



PDFN5X6

Dimensions In Millimeters

SYMBOL	min	max	SYMBOL	min	max	SYMBOL	min	max
A	0.95	1.20	E	5.9	6.1	L2		0.2
b	0.25	0.40	E1	5.7	5.8	$\theta$		13°
c	0.21	0.34	E2	3.34	3.54	P	1.0	1.2
D		5.1	H	0.51	0.71			
D1	4.8	5.0	K	1.1				
D2	3.91	4.20	L	0.51	0.71			
e	1.17	1.37	L1	0.06	0.2			

**Product Summary**

BVDSS	RDSON	ID
30V	4.3mΩ	82A

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	82	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	53	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	155	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	38.8	mJ
$I_{AS}$	Avalanche Current	34	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	37	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	4.6	°C/W

# 80N03NF

## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	4.3	6.2	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	---	5.7	8	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	---	2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	---	67	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.7	---	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	---	8	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	2.4	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	3.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =15A	---	7.1	---	ns
T <sub>r</sub>	Rise Time		---	40	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	15	---	
T <sub>f</sub>	Fall Time		---	6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	814	---	pF
C <sub>oss</sub>	Output Capacitance		---	498	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	41	---	

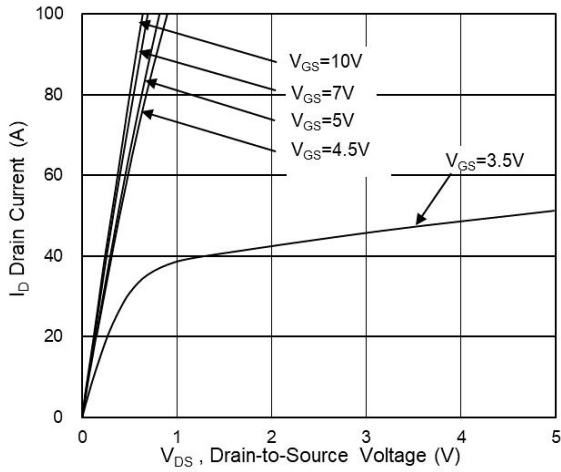
## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	82	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/μs,	---	15	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	25	---	nC

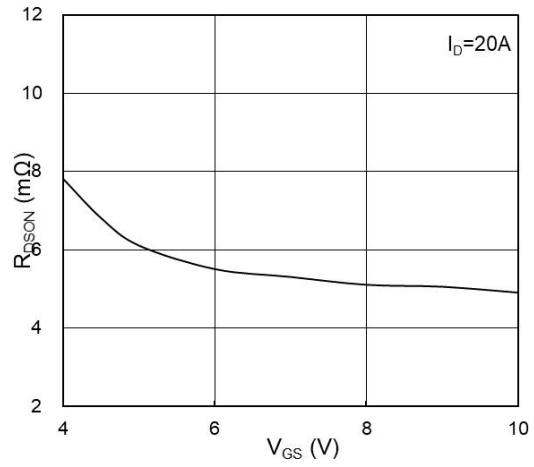
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=24A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

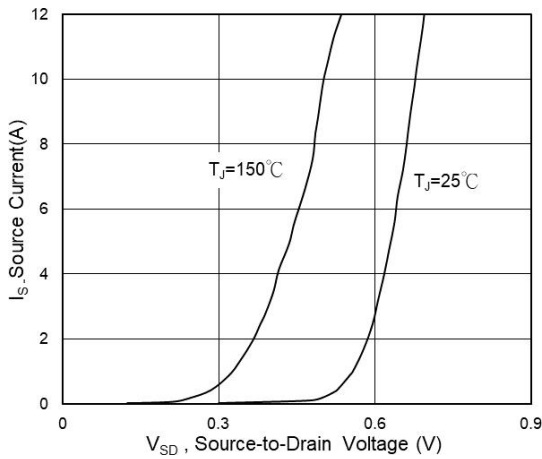
## RATING AND CHARACTERISTIC CURVES (80N03NF)



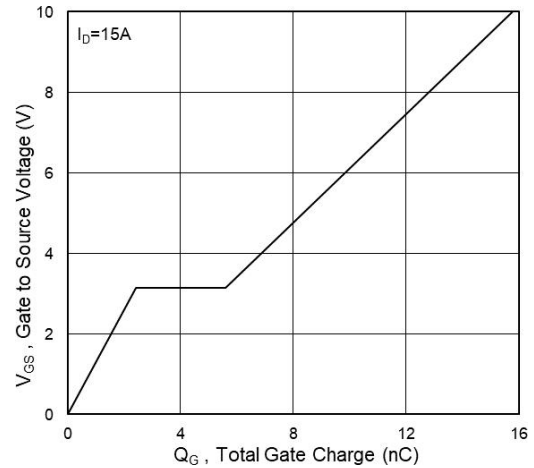
**Fig.1 Typical Output Characteristics**



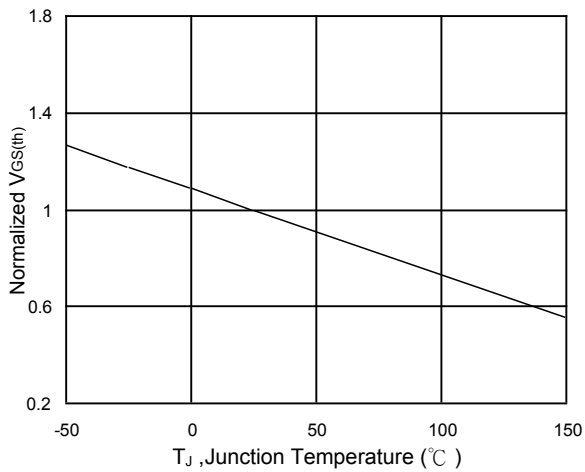
**Fig.2 On-Resistance vs G-S Voltage**



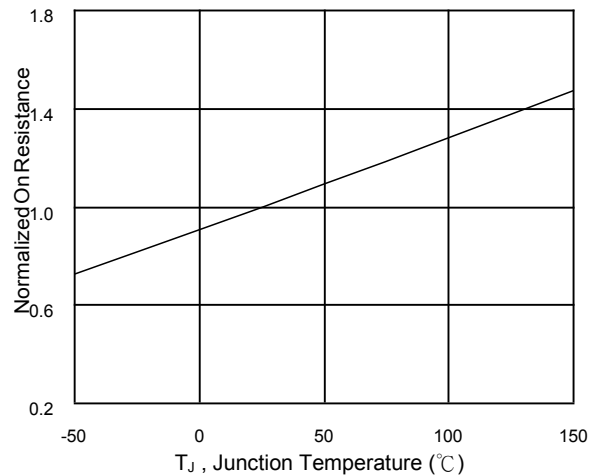
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**

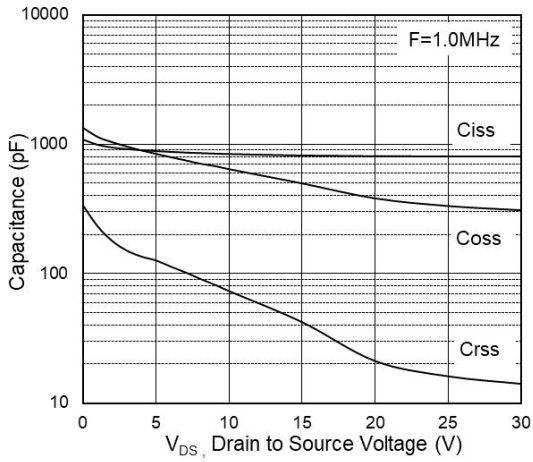


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

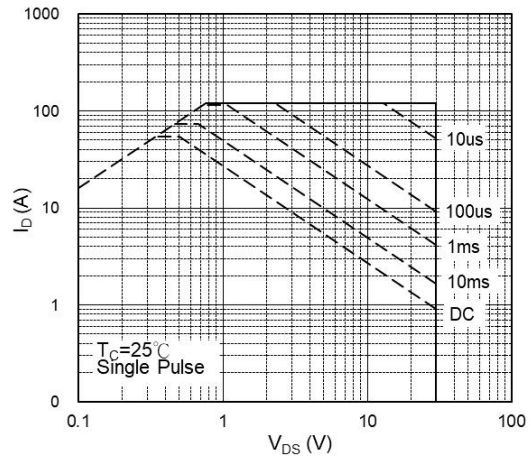


**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

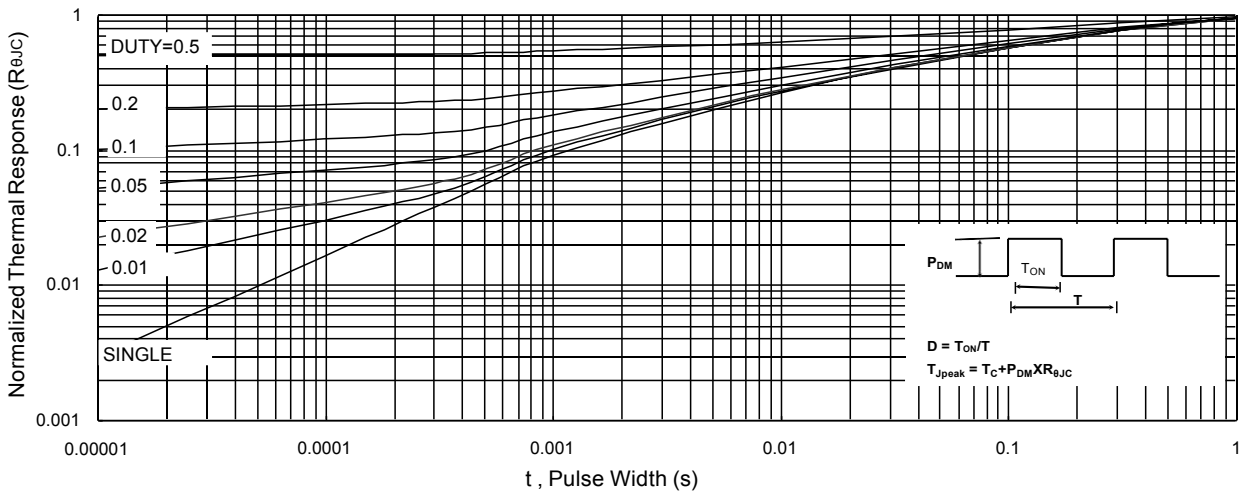
## RATING AND CHARACTERISTIC CURVES (80N03NF)



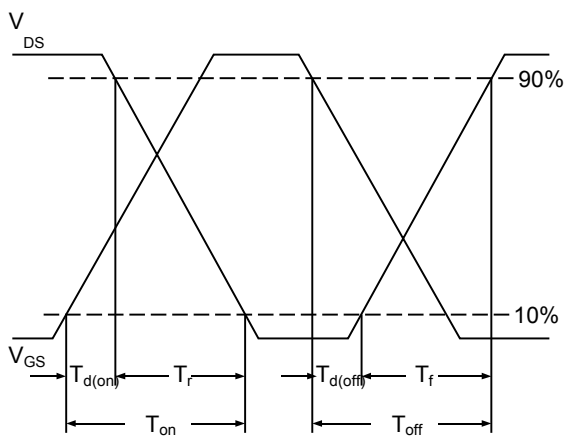
**Fig.7 Capacitance**



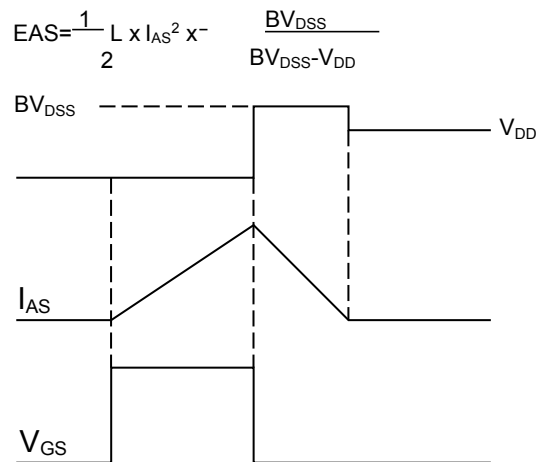
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**